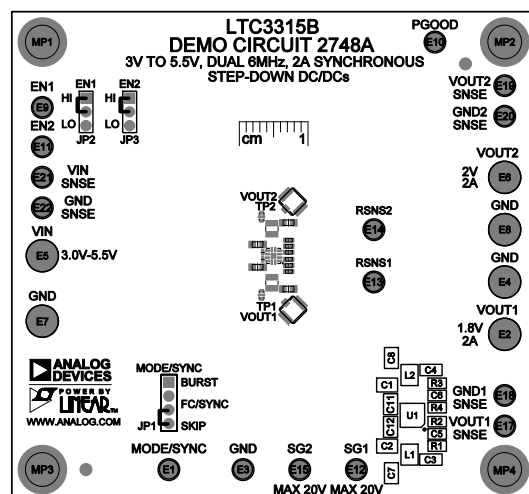
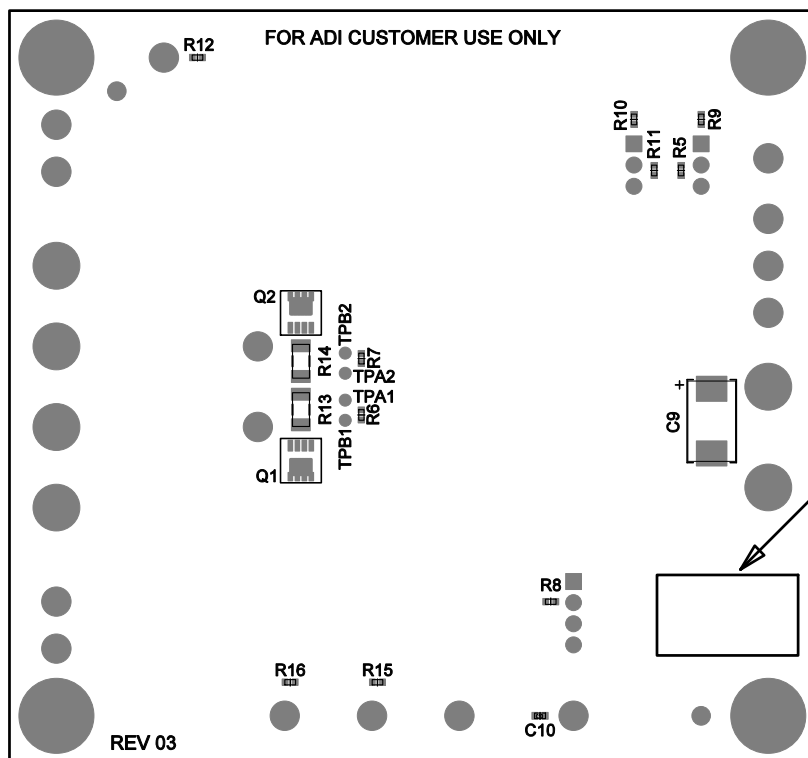


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	03	PRODUCTION	KY	3-31-2020

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS  
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.  
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.





## APPROVALS

PCB DES. NC

APP ENG. KY

SCALE = NONE



FOR ADI CUSTOMER USE ONLY

TITLE: BOTTOM ASSEMBLY DRAWING

3V TO 5.5V, DUAL 6MHz, 2A SYNCHRONOUS  
STEP-DOWN DC/DCs

SIZE  
N/A

IC NO. LTC3315B  
DEMO CIRCUIT 2748A

REV  
03

SHT 2 of 2